L Number	Hits	Search Text	DB	Time stamp
- Number	<del> </del>			2004/04/08 08:51
1	348	1 1 2 2 4 2 2 4 2 2 2 2 2 2 2 2 2 2 2 2	USPAT	
-	258	1	USPAT	2002/07/03 08:58
-	94	(438/110).CCLS.	USPAT	2002/07/03 08:58
_	59	(438/114).CCLS.	USPAT	2002/07/03 08:58
<u>-</u>	681	1 ' .'	USPAT	2002/12/19 14:38
_	1	430/15,110,113,114.0018.		
-	401		USPAT	2001/08/07 15:09
-	272	(438/15,110,113,114.ccls. and test\$3) and	USPAT	2001/08/07 15:10
1		(dice\$4 or cut\$5)		
_	901	438/15,110,113,114.ccls.	USPAT;	2002/02/04 09:53
		130/23/220/223/221100231	EPO; JPO;	2002/02/01 03:33
			DERWENT	
-	460	438/15,110,113,114.ccls. and test\$3	USPAT;	2002/02/04 09:54
			EPO; JPO;	
			DERWENT	Į.
l <u>-</u>	325	(438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:26
	323		1 .	2002/02/03 08.20
	Ì	(dic\$5 or cut\$5)	EPO; JPO;	†
			DERWENT	İ
-	5	(("6077757") or ("6335224") or ("6309943")	USPAT	2004/04/08 10:12
†		or ("6309909") or ("6326697")).PN.	1	
	-		******	0000/00/05 00 40
1 - I	7	(, ,,,,,,,, , ,,,,,,,,,,,,,,,,,,,,,,,	USPAT	2002/02/05 09:49
	1	or ("6309909") or ("6326697") or ("5858815")	!	
	1	or ("5137836")).PN.	1	
<u>-</u>	326	(438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:28
	520			2002,02,03 00.28
	1	(dic\$5 or cut\$5)	EPO; JPO;	1
į l	1	l	DERWENT	
-	0	((438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:33
1		(dic\$5 or cut\$5) ) and (magnet\$7 adj	EPO; JPO;	
		align\$5)	DERWENT	
	170		II'	2000/00/05 00 30
-	170	((438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:32
		(dic\$5 or cut\$5) ) and (align\$5)	EPO; JPO;	
			DERWENT	
_	2705	magnet\$7 adj align\$5	USPAT;	2002/02/05 08:56
				2002,02,03 00.30
			EPO; JPO;	
			DERWENT	
-	0	(magnet\$7 adj align\$5) and (wafer adj20	USPAT;	2002/02/05 08:37
		dielectric adj tape)	EPO; JPO;	
1		and the same of th	DERWENT	
	0	for odino dialoghuic odi bono	1	2002/02/05 00 27
	1	wafer adj20 dielectric adj tape	USPAT;	2002/02/05 08:37
			EPO; JPO;	
			DERWENT	
-	0	wafer adj dielectric adj tape	USPAT;	2002/02/05 08:38
		.,	EPO; JPO;	
		(	DERWENT	
<b>-</b>	248	(magnet\$7 adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
			EPO; JPO;	
[			DERWENT	
_	l 0	((magnet\$7 adj align\$5) and ring) and	USPAT;	2002/02/05 08:49
	1	(charged adj slot)	,	2002/02/03 08:49
		(cuarded adl sinc)	EPO; JPO;	
			DERWENT	
-	0	(magnet\$7 adj align\$5) and (charged adj	USPAT;	2002/02/05 08:49
		slot)	EPO; JPO;	,
1	1		DERWENT	
!		/magnetics and alients and alients	1	2000/00/05 00 ==
-	613	(magnet\$7 adj align\$5) and ring	USPAT;	2002/02/05 08:50
			EPO; JPO;	ļ i
			DERWENT	
_	47	((magnet\$7 adj align\$5) and ring) and	USPAT;	2002/02/05 08:51
	l - '	semiconductor	1	===== , == , == = = =
		Bemiconductor	EPO; JPO;	
	İ	l ,	DERWENT	l
-	3066	optically adj align\$5	USPAT;	2002/02/05 08:56
			EPO; JPO;	
			DERWENT	
	(10	(onticelly add plicable) and remised as		2002/02/05 00 ==
-	612	(optically adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
			EPO; JPO;	
			DERWENT	
-	8	(("6077757") or ("6335224") or ("6309943")	USPAT	2003/06/02 08:10
		or ("6309909") or ("6326697") or ("5858815")		=====
		or ("5137836") or ("4781969")).PN.		ı

-	10260	wood.inv.	USPAT;	2002/07/03 08:13
ŀ	i		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		,	IBM TDB	
1 _	539	wood.inv. and alan	USPAT:	2002/07/03 08:13
-	339	wood.inv. and alan		2002/07/03 08.13
	ŀ		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	232	(wood.inv. and alan) and (micron adj	USPAT;	2002/07/03 08:14
		technology)	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	1	("6268650").PN.	USPAT	2004/04/06 13:58
_				
-	425	(438/15).CCLS.	USPAT	2002/07/08 08:43
-		(438/113).CCLS.	USPAT	2002/07/08 08:57
-	140	(438/110).CCLS.	USPAT	2002/07/08 08:57
-	90	(438/114).CCLS.	USPAT	2002/07/08 08:57
-	425	(438/15).CCLS.	USPAT	2002/07/08 08:43
-	331	(438/113).CCLS.	USPAT	2002/07/08 08:57
1 -	140	(438/110).CCLS.	USPAT	2002/07/08 08:57
1_	90	(438/114).CCLS.	USPAT	2002/07/08 08:37
1	4		1 '	
-	13	(("6389689") or ("5977629") or ("5796170")	USPAT	2002/07/08 10:35
	1	or ("6326700") or ("6268650") or ("5858815")		
		or ("5817535") or ("5770032") or ("4781969")	1	
	1	or ("5073840") or ("5696033") or ("5834839")	1	
		or ("6160714")).PN.	1	
-	8	(("6309909") or ("5858815") or ("5137836")	USPAT	2002/07/09 09:56
1		or ("6077757") or ("6326697") or ("6165885")		
	Į.	or ("5834320") or ("4781969")).PN.		
	_		HCDATE.	2002/12/19 15:00
-	0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 15:00
		(dielectric adj (layer or film))) same	US-PGPUB;	
İ		test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
			DERWENT;	
	ì		IBM TDB	ļ
_	l 0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:07
i		(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
		ceseys same (eacy) or areys or separates;	DERWENT;	İ
			IBM_TDB	0000/10/10 14 07
-	19	wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:07
Į.		(dielectric adj (layer or film))	US-PGPUB;	
			EPO; JPO;	
	1	·	DERWENT;	
	1		IBM TDB	
_	0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:38
	1	(dielectric adj (layer or film))) same	US-PGPUB;	= : : : : : : : : : : : : : : : : : :
1	1			
	1	test\$3	EPO; JPO;	
	!		DERWENT;	
	1		IBM_TDB	
-	963	438/15,110,113,114.ccls.	USPAT	2002/12/19 14:38
-	1212	438/15,110,113,114.ccls.	USPAT;	2002/12/19 14:38
			US-PGPUB;	1
	1		EPO; JPO;	
	1		DERWENT;	
	1 _	420/15 110 112 1141 1/5 1/	IBM_TDB	0000/10/10 11 15
-	0	438/15,110,113,114.ccls. and ((wafer adj	USPAT;	2002/12/19 14:40
1		(bond\$3 or attach\$3) near4 (dielectric adj	US-PGPUB;	
		(layer or film))) same test\$3)	EPO; JPO;	
	1		DERWENT;	]
			IBM TDB	
_	9	(wafer adj (dielectric adj (layer or film)))	USPAT;	2002/12/20 08:18
	1	same test\$3	US-PGPUB;	-002, 12, 20 00.10
	İ	Build Cobbys	I '	
			EPO; JPO;	
			DERWENT;	i
			IBM_TDB	

		1 //0-223-201		1
-	13	' ' ' '   '   '   '   '   '   '   '	USPAT	2002/12/19 15:19
		or ("5977629") or ("6326700") or ("6268650")		
		or ("5858815") or ("5817535") or ("5770032") or ("5796170") or ("4781969") or ("5073840")		
		or ("5696033")).PN.		
-	85		USPAT;	2002/12/20 08:42
		(cut\$3 or dic\$3 or slic\$3)	US-PGPUB;	,,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	78		USPAT;	2002/12/20 09:38
		(cut\$3 or dic\$3 or slic\$3)) and semiconductor	US-PGPUB; EPO; JPO;	
		Semiconductor	DERWENT;	
			IBM TDB	
-	348		USPAT;	2002/12/20 09:35
		film))) same test\$3	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
-	322	((wafer same (dielectric adj (layer or	USPAT;	2002/12/20 09:38
		film))) same test\$3 ) and semiconductor	US-PGPUB;	2002, 22, 20 05.30
		· ·	EPO; JPO;	
			DERWENT;	
		///wafer game /dieloghair add /lawar ar	IBM_TDB	2002/12/20 00 22
_	98	(((wafer same (dielectric adj (layer or film))) same test\$3 ) and semiconductor) and	USPAT; US-PGPUB;	2002/12/20 09:39
		(cut\$3 or dic\$3)	EPO; JPO;	
		, , , , , , , , , , , , , , , , , , , ,	DERWENT;	
			IBM_TDB	
-		("6424023").PN.	USPAT	2002/12/20 10:24
-	3	(("5897337") or ("5858815") or	USPAT	2002/12/23 11:53
_	2	("6389689")).PN.   (("5897337") or ("6389689")).PN.	USPAT	2002/12/23 11:53
-	9187		USPAT;	2002/12/23 11:53
		semiconductor	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
<u> </u>	4418	(((balls adj grid adj arrays) or (BGA)) and	IBM_TDB USPAT;	2003/05/20 08:02
	1110	semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB;	2005/05/20 00.02
		separat\$5)	EPO; JPO;	
			DERWENT;	
	4476	///halla add mid add amaran) an (DG1)) and	IBM_TDB	2002/05/20 00 04
_	4476	(((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or	USPAT; US-PGPUB;	2003/05/20 08:04
		separat\$5 or saw\$4)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	955		USPAT;	2003/05/20 08:04
		semiconductor) and (dic\$4 or cut\$4 or   separat\$5)) and (metal adj (film or layer))	US-PGPUB;	
		separaces;; and (mecar adj (film or layer))	EPO; JPO; DERWENT;	
		·	IBM TDB	
-	970		USPAT;	2003/05/20 08:04
		semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB;	
		separat\$5 or saw\$4)) and (metal adj (film or	EPO; JPO;	
		layer))	DERWENT; IBM TDB	
_	1	("20010052642").PN.	US-PGPUB	2003/05/20 08:12
-	472		USPAT;	2003/05/20 08:52
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	. ,
		adj arrays) or (BGA)) and semiconductor and	EPO; JPO;	
		(dic\$4 or cut\$4 or separat\$5)	DERWENT;	
l _	233	(wafer and (metal adj (film or layer)) and	IBM_TDB USPAT;	2004/01/12 08:09
_	233	(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	2004/01/12 00:09
		adj arrays) or (BGA)) and semiconductor and	EPO; JPO;	
		(dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616	IBM_TDB	

-	212	((wafer and (metal adj (film or layer)) and	USPAT;	2003/05/21 08:23
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and	EPO; JPO; DERWENT;	
	1	@ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)	IBM TDB	
_	206		USPAT;	2003/05/20 09:06
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor and	EPO; JPO;	
į		(dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616) and (dic\$5 or cut\$6)	IBM_TDB	
-	1	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/05/20 10:06
		(film or layer)) same (attach\$5 or bond\$4)	US-PGPUB;	
		same ((balls adj grid adj arrays) or (BGA)) same (dic\$4 or cut\$4 or separat\$5)) same	EPO; JPO; DERWENT;	
		(dic\$5 or cut\$6 or saw\$5)) and @ad<=20000616	IBM TDB	
-	212		USPAT;	2003/05/21 09:00
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
İ		adj arrays) or (BGA)) and semiconductor and	EPO; JPO;	
		(dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)	IBM_TDB	
-	172	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USPAT;	2003/05/21 09:24
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and	EPO; JPO; DERWENT;	
		@ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)	IBM TDB	
		) and dic\$5	15.1_155	
-	92		USPAT;	2003/05/21 09:35
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor and	EPO; JPO;	
		(dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)	IBM_TDB	
	70	) and (dicing or diced)	HICDAM.	2003/05/21 00.36
-	/ /	((((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj	USPAT; US-PGPUB;	2003/05/21 09:36
		grid adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
1		@ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)	IBM_TDB	
		) and (dicing or diced)) and (individual\$3	_	
		or each)	_	
-	70	1	USPAT;	2003/05/21 09:36
1		and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor	US-PGPUB;	
		and (dic\$4 or cut\$4 or separat\$5)) and	EPO; JPO;   DERWENT;	
		@ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)	IBM_TDB	
		) and (dicing or diced)) and (individual\$3)		
-	6	((((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:37
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)   ) and (dicing or diced)) and (individual\$3	IBM_TDB	
		adj device)		
-	2	(("6344401") or ("6566745")).PN.	USPAT	2004/01/12 07:56
-	241	(wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12 08:10
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or ("BGA")) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
	,	@ad<=20000616	IBM_TDB	2002/10/22 10:26
1		((wafer same (metal adj (film or layer)) same (attach\$5 or bond\$4) same ((balls adj	USPAT; US-PGPUB;	2003/10/23 10:36
		grid adj arrays) or ("BGA")) same	EPO; JPO;	
		semiconductor same (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5))) and @ad<=20000616	IBM_TDB	
-	2	(("6153448") or ("20020011859")).PN.	USPAT;	2003/10/24 12:35
			US-PGPUB	
-	4		USPAT;	2003/10/24 14:07
		("6064217") or ("5475317")).PN.	US-PGPUB	2004/01/12 00 14
-	3	(("6344401") or ("6165885") or ("5834320")).PN.	USPAT	2004/01/12 09:14
L	L	\ JUJIJEU //.EN.	L	

-	244	(wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12 08:03
	,	(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor and	EPO; JPO;	
		(dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616	IBM_TDB	
-	244		USPAT;	2004/04/06 08:33
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor and	EPO; JPO;	
		(dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616	IBM_TDB	
-	166		USPAT;	2004/01/12 08:05
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor and	EPO; JPO;	
		(dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616 ) and align\$6	IBM_TDB	
-	688	(438/455).CCLS.	USPAT;	2004/01/12 08:08
ĺ			US-PGPUB;	
	İ		EPO; JPO;	
			DERWENT;	
i			IBM TDB	
-	12	438/455,456,457,458,459,460,461,462,464.ccls.	USPAT;	2004/01/12 08:11
	1	and (wafer and (metal adj (film or layer))	US-PGPUB;	
	İ	and (attach\$5 or bond\$4) and ((balls adj	EPO; JPO;	
	1	grid adj arrays) or ("BGA")) and (dic\$4 or	DERWENT;	
	1	cut\$4 or separat\$5)) and @ad<=20000616	IBM TDB	
-	97		USPAT;	2004/01/12 08:52
	]	or layer)) and (attach\$5 or bond\$4) and	US-PGPUB;	
•	1	((balls adj grid adj arrays) or ("BGA")) and	EPO; JPO;	
1	1	(dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616	IBM TDB	
_	348		USPAT;	2004/04/06 08:36
1		or layer)) and (attach\$5 or bond\$4) and	US-PGPUB;	2004/04/00 00:30
		((balls adj grid adj arrays) or (BGA)) and	EPO; JPO;	
	[	semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616	IBM TDB	
_	229		USPAT;	2004/04/06 08:36
	229	or layer)) and (attach\$5 or bond\$4) and	US-PGPUB;	2002/04/00 08:36
		((balls adj grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
1_	85	separat\$5)) and @ad<=20000616 ) and test\$4 (((wafer and ((metal or conductive) adj	<pre>IBM_TDB USPAT;</pre>	2004/04/06 08:37
	63	(film or layer)) and (attach\$5 or bond\$4)		2004/04/00 08:3/
		and ((balls adj grid adj arrays) or (BGA))	US-PGPUB;	
	İ	and ((balls ad) grid ad) arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or	EPO; JPO;	
			DERWENT;	
		separat\$5)) and @ad<=20000616 ) and test\$4)	IBM_TDB	
_	86	and (input same output) (((wafer and ((metal or conductive) adj	HCDATT-	2004/04/06 00:44
	"	(film or layer)) and (attach\$5 or bond\$4)	USPAT;	2004/04/06 08:44
		and ((balls adj grid adj arrays) or (BGA))	US-PGPUB;	
			EPO; JPO;	
	1	and semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
1	[	separat\$5)) and @ad<=20000616 ) and test\$4)	IBM_TDB	
1_	7.0	and (input and output)	IIODAM	2004/04/06 11 01
1	78	((((wafer and ((metal or conductive) adj	USPAT;	2004/04/06 11:21
		(film or layer)) and (attach\$5 or bond\$4)	US-PGPUB;	
		and ((balls adj grid adj arrays) or (BGA))	EPO; JPO;	
		and semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616 ) and test\$4)	IBM_TDB	
	ا م	and (input and output)) and (cut\$5 or dic\$6)	IIODAM	2004/04/25 11 25
-	24	(((((wafer and ((metal or conductive) adj	USPAT;	2004/04/06 11:21
		(film or layer)) and (attach\$5 or bond\$4)	US-PGPUB;	
		and ((balls adj grid adj arrays) or (BGA))	EPO; JPO;	İ
	1	and semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616 ) and test\$4)	IBM_TDB	
		and (input and output)) and (cut\$5 or		
	ا ہ ا	dic\$6)) and (conductive adj trace)	IIODAT	2004/04/00 12 56
-	"	(("5858815") or ("4781969") or ("5073840")	USPAT	2004/04/08 13:56
]	,,	or ("5770032") or ("5817535")).PN.	HODAM	2004/04/02 12 22
-	10	(("5073840") or ("5817535") or ("5858815")	USPAT	2004/04/08 13:29
		or ("6426642") or ("6214716") or ("6188232")		
		or ("6163956") or ("6150193") or ("6060891")		
L	L	or ("6004867")).PN.		

-	10	(("5073840" "5817535" "5858815" "6426642"	USPAT;	2004/04/08 (	09:30
		"6214716" "6188232" "6163956" "6150193"	US-PGPUB;		
		"6060891" "6004867").pn.) and test\$5 and	EPO; JPO;		
		(cut\$5 or dic\$6 or seperat\$5 or saw\$4)	DERWENT;		
		•	IBM TDB		1
-	6	((("5073840" "5817535" "5858815" "6426642"	USPAT;	2004/04/08 (	09:30
		"6214716" "6188232" "6163956" "6150193"	US-PGPUB;		
		"6060891" "6004867").pn.) and test\$5 and	EPO; JPO;		
		(cut\$5 or dic\$6 or seperat\$5 or saw\$4)) and	DERWENT;		
		cut\$6	IBM_TDB	_	